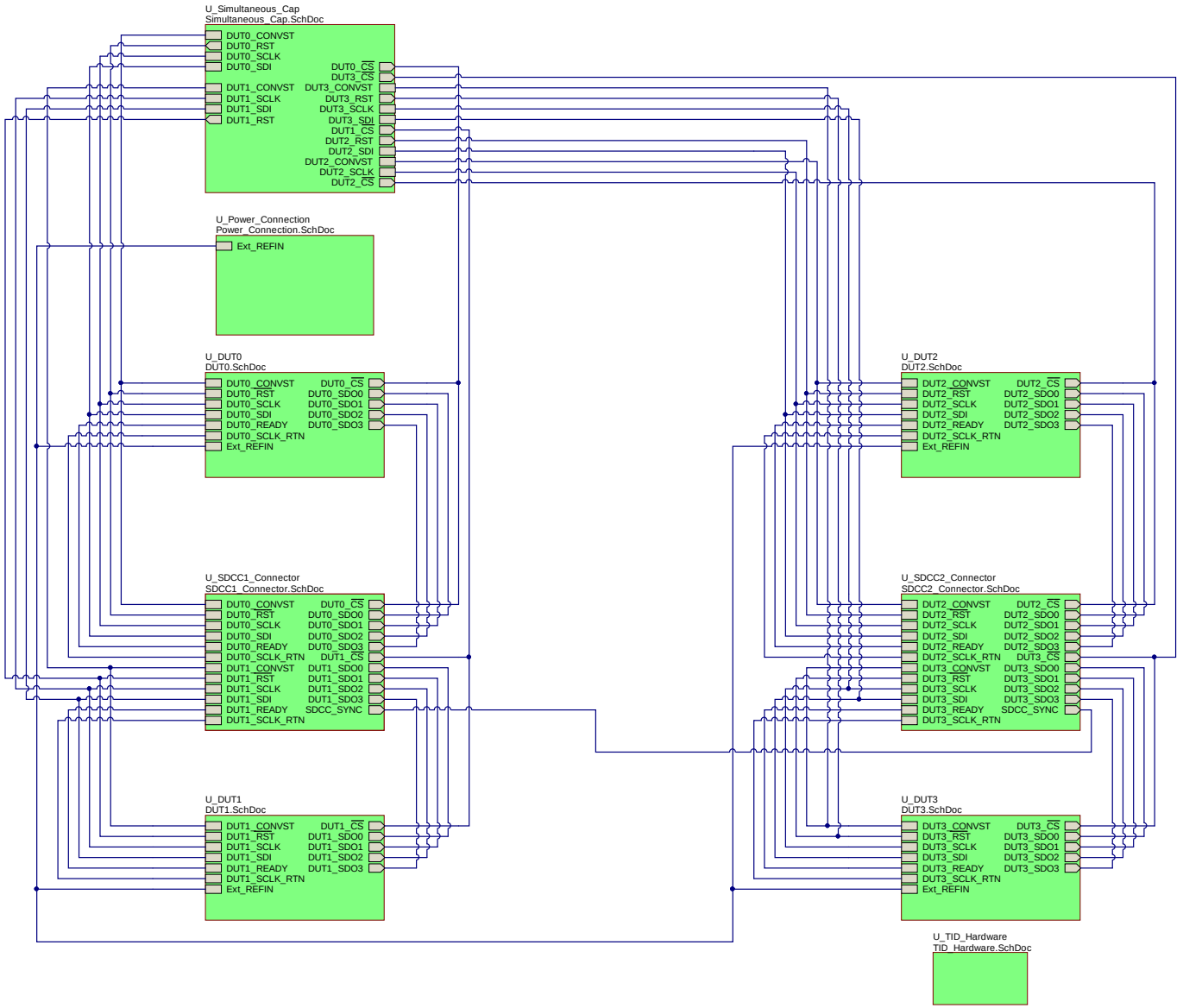

Revision History	
Revision	Notes

Orderable: N/A		Designed for:Public Release	Mod. Date: 6/28/2016
TID #: TIPD211		Project Title:TIPD211	
Number: TIPD211	Rev: E1	Sheet Title:	
SVN Rev: Not in version control		Assembly Variant:[No Variations]	Sheet:1 of 10
Drawn By:		File: CoverSheet.SchDoc	Size: B
Engineer: SHRIDHAR MORE		Contact: http://www.ti.com/support	

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H1
9774050360R

H2
9774050360R

H3
9774050360R

H4
9774050360R

@H1
1902C

@H2
1902C

@H3
1902C

@H4
1902C

FID1 FID2 FID3
FID4 FID5 FID6

PCB Number: TIPD211
PCB Rev: E1

PCB
LOGO
Texas Instruments

PCB
LOGO
Pb-Free Symbol

You should delete the nylon screws/standoffs and/or the bumpons as needed for your design (or substitute other parts from Hardware.IntLib). Bumpons are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You can delete this note too.

Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

ZZ1
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ2
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ3
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Orderable: N/A		Designed for:Public Release	Mod. Date: 3/24/2016
TID #: TIPD211		Project Title:TIPD211	
Number: TIPD211	Rev: E1	Sheet Title:	
EVM Rev: Not in version control		Assembly Variant:[No Variations]	Sheet:2 of 10
Drawn By:		File: TID_Hardware.SchDoc	Size: B
Engineer: SHRIDHAR MORE		Contact: http://www.ti.com/support	

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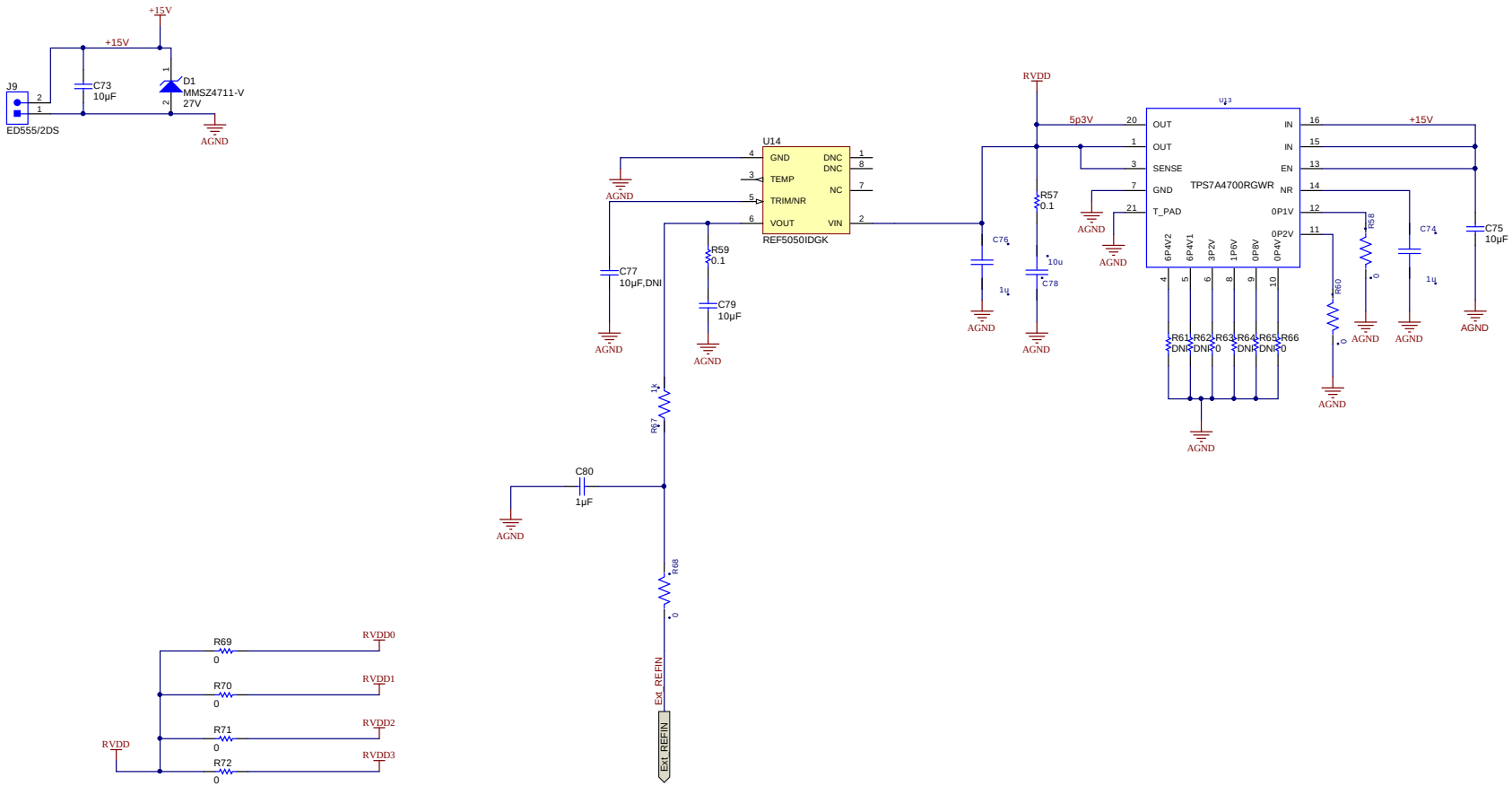

Orderable: N/A		Designed for: Public Release	Mod. Date: 11/18/2016
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Number: TIPD211	Rev: E1	Sheet Title:	
BOM Rev: Not in version control		Assembly Variant: [No Variations]	Sheet: 3 of 10
Drawn By:		File: Power_Connection.SchDoc	Size: B
Engineer: SHRIDHAR MORE		Contact: http://www.ti.com/support	

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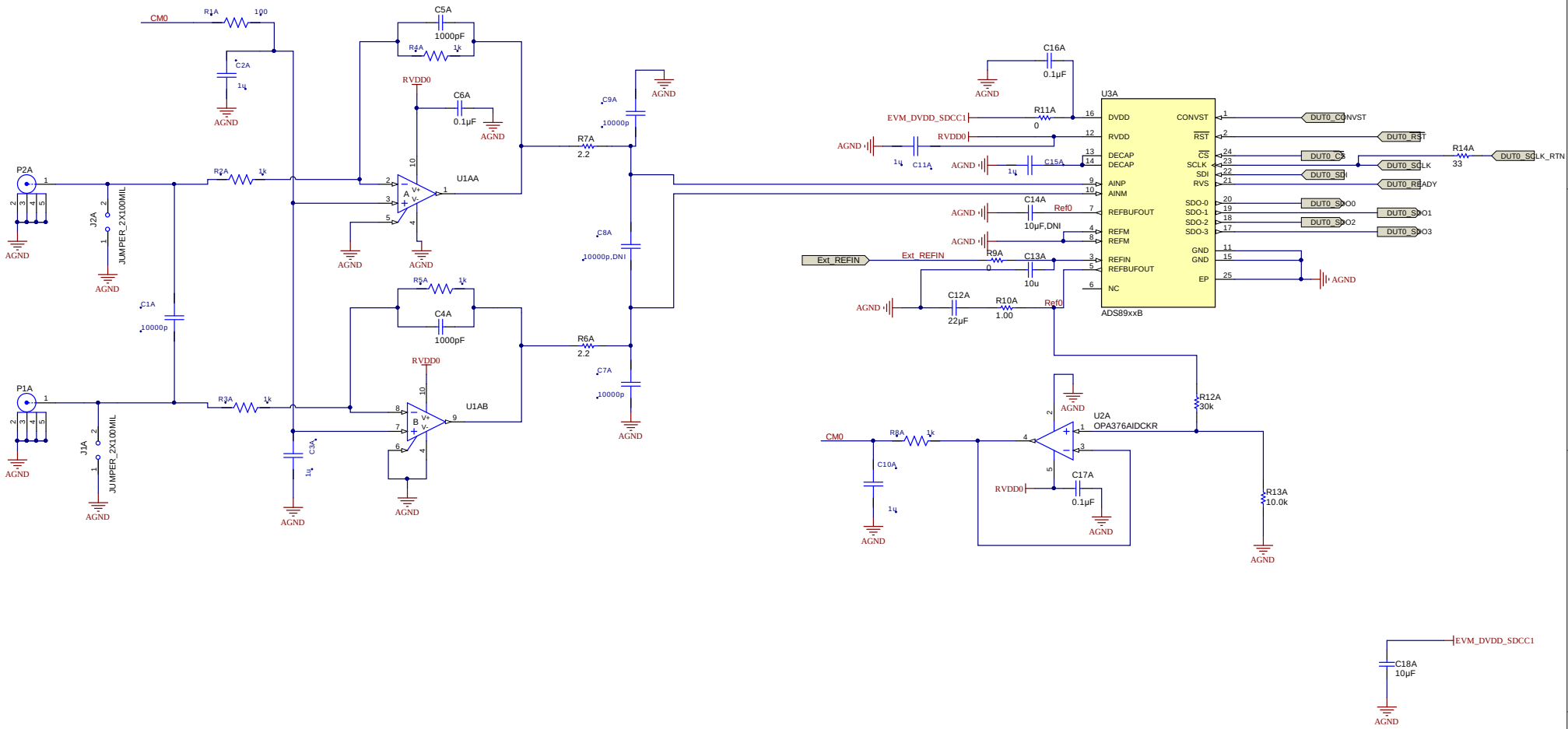

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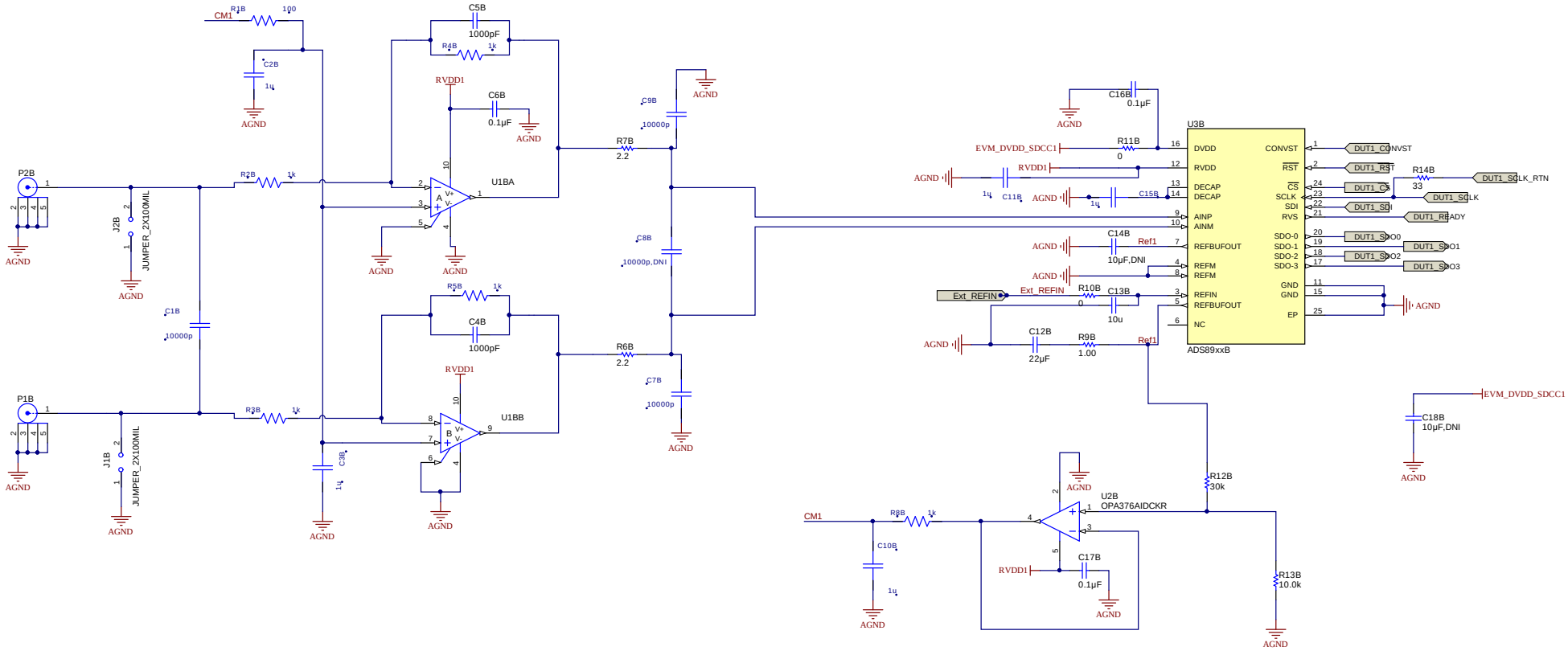
Number: TIPD211	Rev: E1	Sheet Title:	
BOM Rev: Not in version control		Assembly Variant:[No Variations]	Sheet:4 of 10
Drawn By:		File: DUT0.SchDoc	Size: B
Engineer: SHRIDHAR MORE		Contact: http://www.ti.com/support	



Orderable: N/A		Designed for:Public Release	Mod. Date: 11/4/2016
TID #: TIPD211		Project Title:TIPD211	
Number: TIPD211	Rev: E1	Sheet Title:	
EVM Rev: Not in version control		Assembly Variant:[No Variations]	Sheet:5 of 10
Drawn By:		File: DUT1.SchDoc	Size: B
Engineer: SHRIDHAR MORE		Contact: http://www.ti.com/support	

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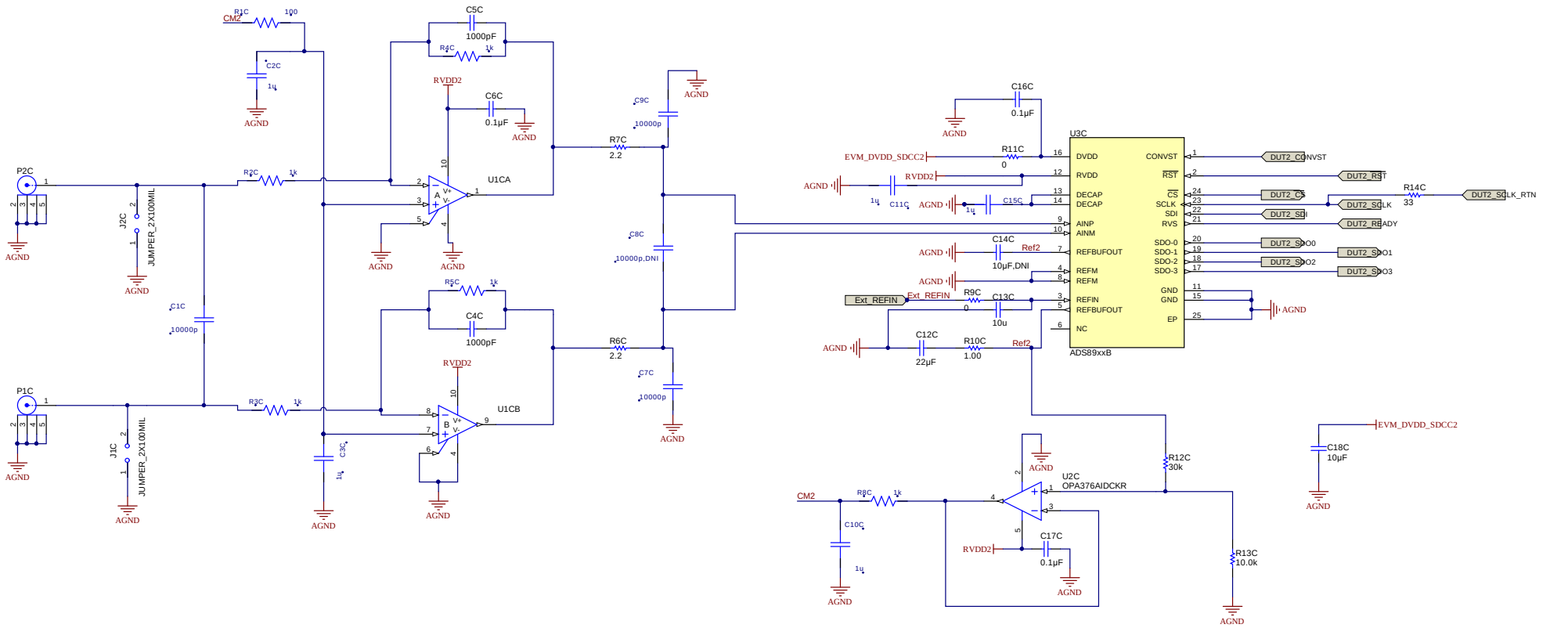

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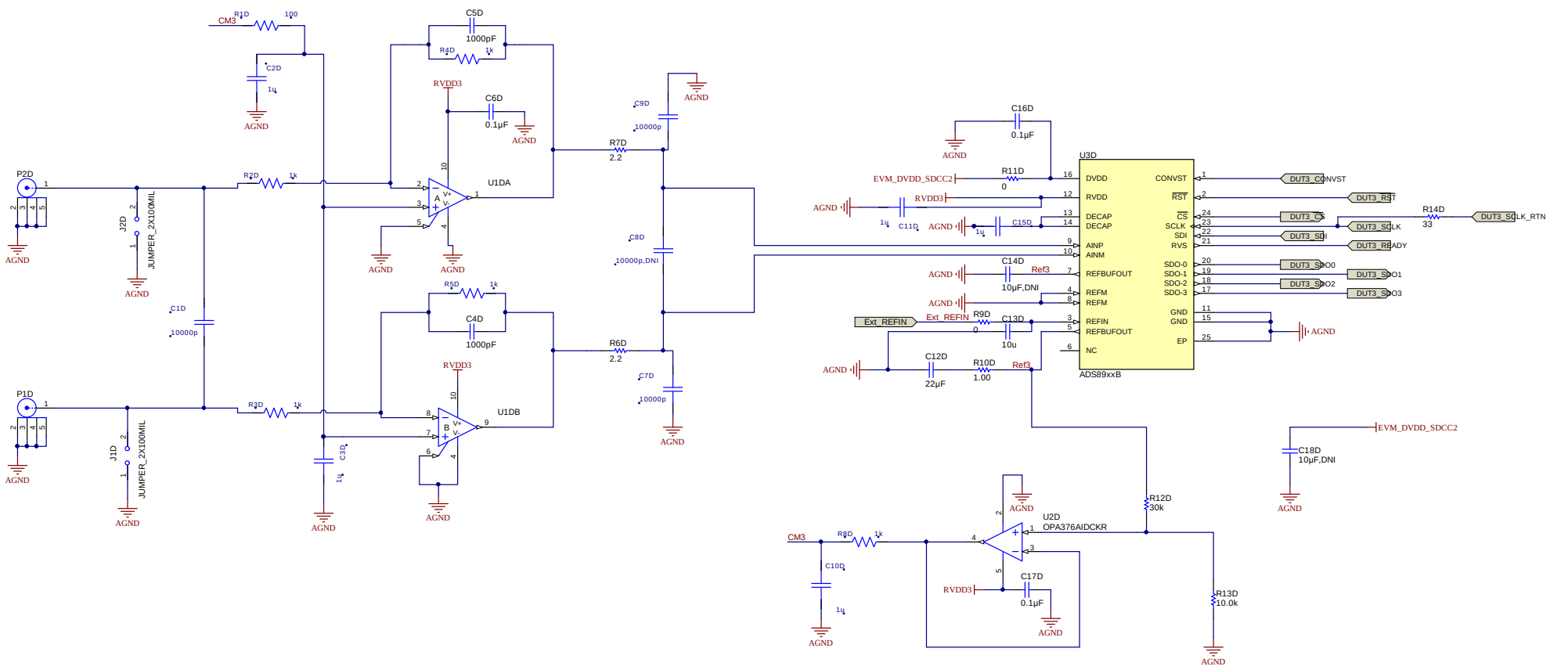
TID #: TIPD211		Project Title:TIPD211	
Number: TIPD211	Rev: E1	Sheet Title:	
BOM Rev: Not in version control		Assembly Variant:[No Variations]	Sheet:6 of 10
Drawn By:		File: DUT2.SchDoc	Size: B
Engineer: SHRIDHAR MORE		Contact: http://www.ti.com/support	



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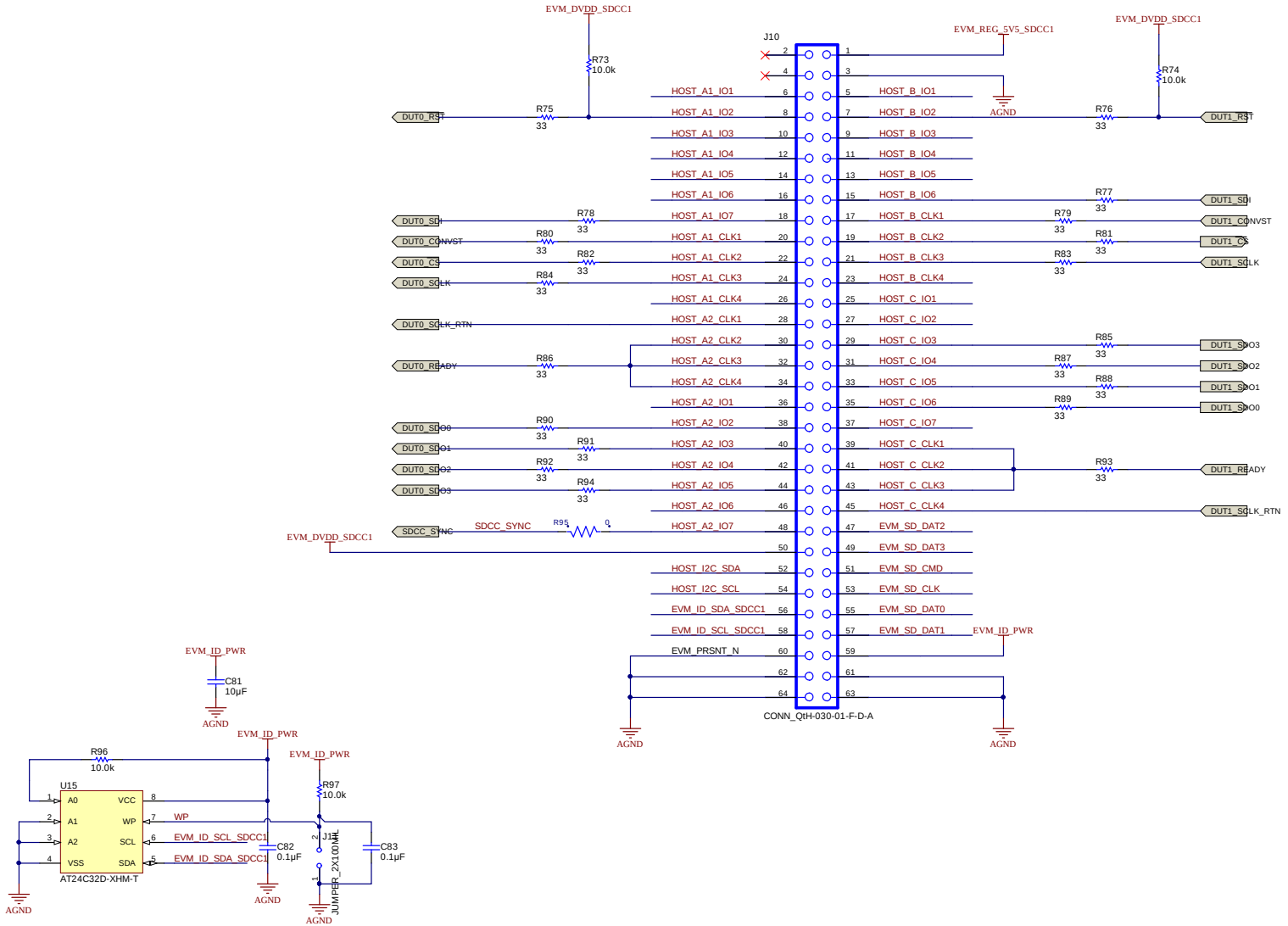
Number: TIPD211	Rev: E1	Sheet Title:	
Variant: Not in version control		Assembly Variant:[No Variations]	Sheet:7 of 10
Drawn By:		File: DUT3.SchDoc	Size: B
Engineer: SHRIDHAR MORE		Contact: http://www.ti.com/support	



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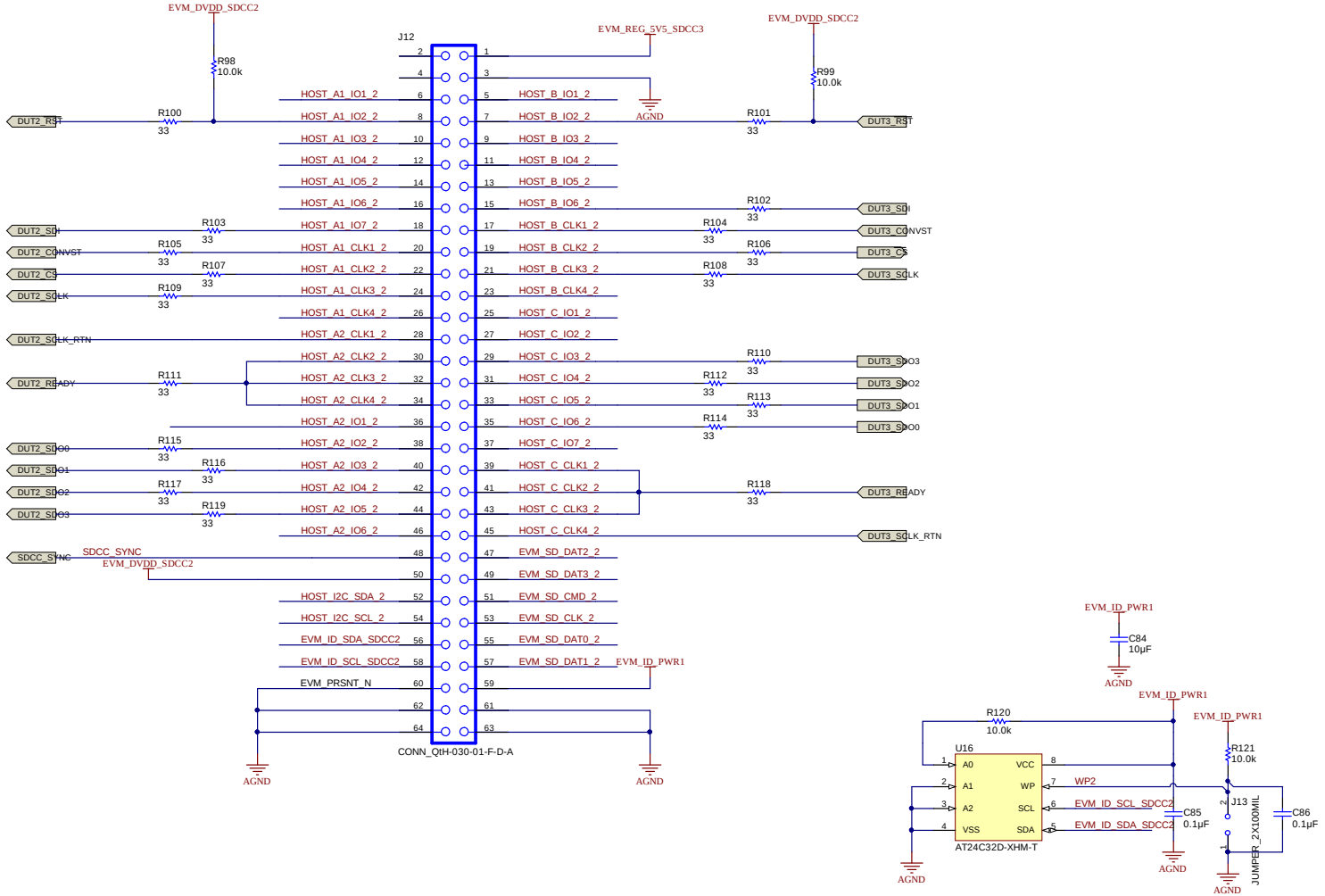
TID #: TIPD211		Project Title:TIPD211	
Number: TIPD211	Rev: E1	Sheet Title:	
EVM Rev: Not in version control		Assembly Variant:[No Variations]	Sheet:8 of 10
Drawn By:		File: SDCC1_Connector.SchDoc	Size: B
Engineer: SHRIDHAR MORE		Contact: http://www.ti.com/support	



Orderable: N/A	Designed for:Public Release	Mod. Date: 3/23/2016
TID #: TIPD211	Project Title:TIPD211	
Number:TIPD211 Rev: E1	Sheet Title:	
BOM Rev: Not in version control	Assembly Variant:[No Variations]	Sheet:9 of 10
Drawn By:	File: SDCC2_Connector.SchDoc	Size: B
Engineer: SHRIDHAR MORE	Contact: http://www.ti.com/support	

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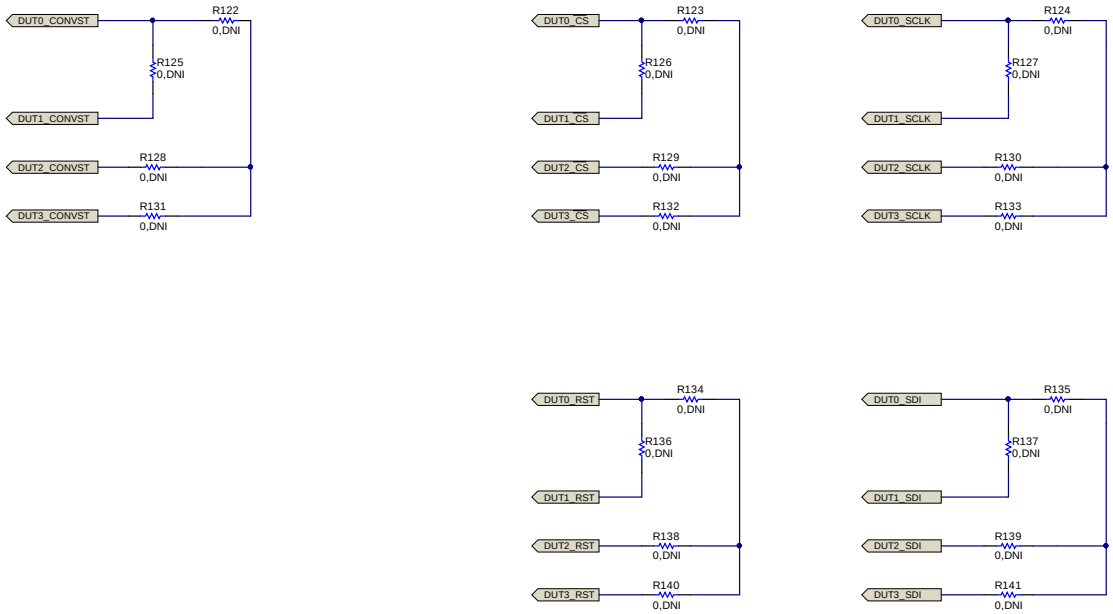

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TID #: TIPD211		Project Title:TIPD211	
Number: TIPD211	Rev: E1	Sheet Title:	
SVN Rev: Not in version control		Assembly Variant:[No Variations]	Sheet:10 of 10
Drawn By:		File: Simultaneous_Cap.SchDoc	Size: B
Engineer: SHRIDHAR MORE		Contact: http://www.ti.com/support	

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